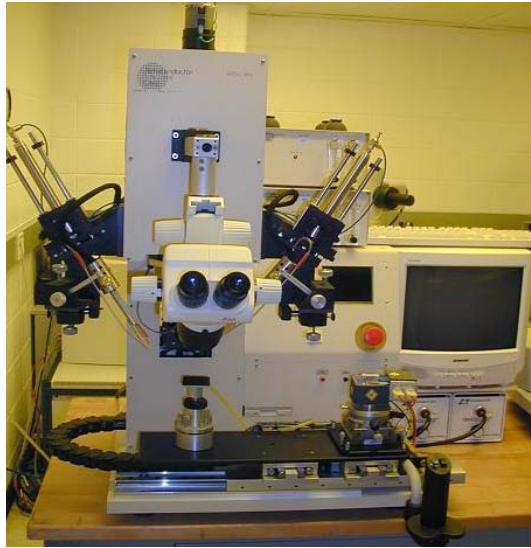


Flip-Chip Bonder



Flip-Chip SEC 860 Omnibonder

The SEC 860 Omnibonder is used for flip-chip integration of the optoelectronic, optical, and electronic devices fabricated in our facility. This bonder is semi-automatic equipment with the ability to perform hot-gas-based localized heating. It offers a passive alignment accuracy of $\pm 5\mu\text{m}$. The head can be modified to perform ultrasonic bonding. Metal-based solders and conductive adhesive based materials have been traditionally used in most of the processes. However, the machine supports a wide variety of load cells, temperatures, and as a result, different technologies and applications can be explored.